

SMD Comm COG Flex, Ceramic, 22 pF, 5%, 100 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1206



| Dimensions | |
|------------|------------------|
| Chip Size | 1206 |
| L | 3.3mm +/-0.4mm |
| W | 1.6mm +/-0.35mm |
| T | 0.78mm +/-0.20mm |
| B | 0.6mm +/-0.25mm |

| Packaging Specifications | |
|--------------------------|-----------|
| Packaging: | Bulk, Bag |
| Packaging Quantity: | 1 |

| General Information | |
|---------------------|---------------------------------|
| Series: | SMD Comm COG Flex |
| Style: | SMD Chip |
| Description: | SMD, MLCC, FT-CAP, Ultra-Stable |
| Features: | FT-CAP, Ultra-Stable |
| RoHS: | Yes |
| Termination: | Flexible Termination |
| Marking: | No |
| AEC-Q200: | No |
| Component Weight: | 15 mg |
| Shelf Life: | 78 Weeks |
| MSL: | 1 |

| Specifications | |
|---|------------------------|
| Capacitance: | 22 pF |
| Measurement Condition: | 1 MHz 1.0Vrms |
| Capacitance Tolerance: | 5% |
| Voltage DC: | 100 VDC |
| Dielectric Withstanding Voltage: | 250 VDC |
| Temperature Range: | -55/+125°C |
| Temperature Coefficient: | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC): | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor: | 0.1% 1 MHz 1.0Vrms |
| Aging Rate: | 0% Loss/Decade Hour |
| Insulation Resistance: | 100 GOhms |

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